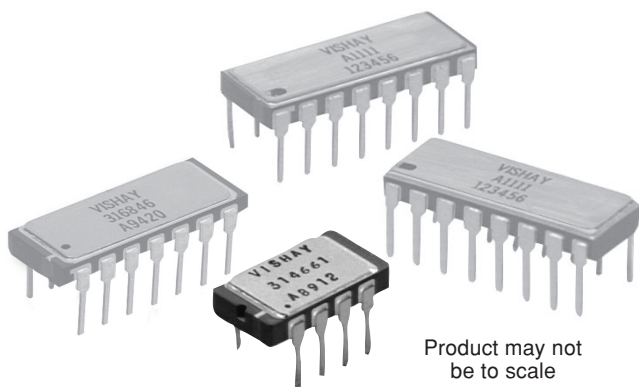


Bulk Metal[®] Foil Technology Dual-In-Line Hermetic Resistor Networks



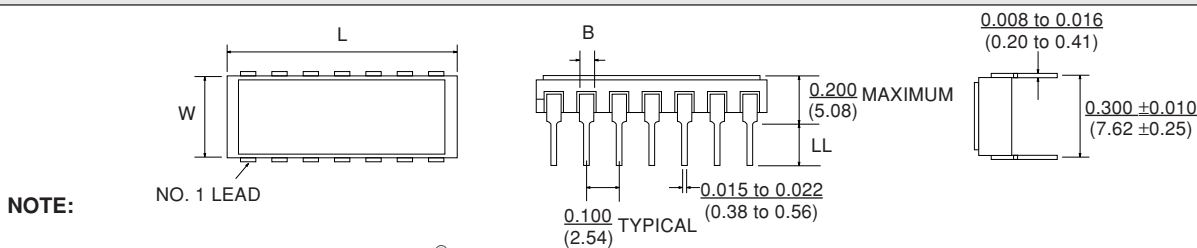
Product may not
be to scale

Vishay Model 1442, 1445 and 1446 networks incorporate all the performance features of Vishay Bulk Metal[®] Foil technology. The 8, 14 and 16 pin side brazed DIPs are a ceramic package. Ceramic has the advantage of electrical isolation on the underside, and, in DIP form, a favorable pin arrangement when two networks are to be placed side by side and connected together.

Review data sheet "7 Technical Reasons to Specify Bulk Metal[®] Foil Resistor Networks."

Networks are built to your requirements. Send your schematic and electrical requirements to the Applications Engineering Department. (See data sheet "Network Worksheet.") A unique part number will be assigned which defines all aspects of your network.

FIGURE 1 - PACKAGE SIZES AND CHARACTERISTICS



VISHAY MODEL	NO. OF PINS	MAXIMUM DIMENSIONS in Inches (mm)				CHIP CAPACITY		MAXIMUM POWER RATING (WATTS) @ +70°C
		L	W	B	LL	V5X5	V15X5	
1442	8	0.520 ± 0.020 (13.21 ± 0.51)	0.295 ± 0.010 (7.49 ± 0.25)	0.054 (1.37)	0.125 minimum (3.18)	12	4	0.4
1445	14	0.740 ± 0.045 (18.80 ± 1.14)	0.270 + 0.035/-0.030 (6.86 + 0.89/-0.76)	0.046 (1.17)	0.135 + 0.015/-0.010 (3.43 + 0.38/-0.25)	30	10	1.2
1446	16	0.780 ± 0.030 (19.81 ± 0.76)	0.290 ± 0.008 (7.37 ± 0.20)	0.040 to 0.070 (1.01 to 1.78)	0.135 + 0.015/-0.010 (3.43 + 0.38/-0.25)	36	12	1.4

FIGURE 2 - SAMPLE CIRCUIT DESIGN AND CHIP LAYOUT

NOTE:

Usable area is represented by the dotted lines—a rectangle 0.150 Inches x 0.200 Inches. Illustrations not to scale. Chips shown undersize for clarity. Drawing view is from the top looking down into the package.

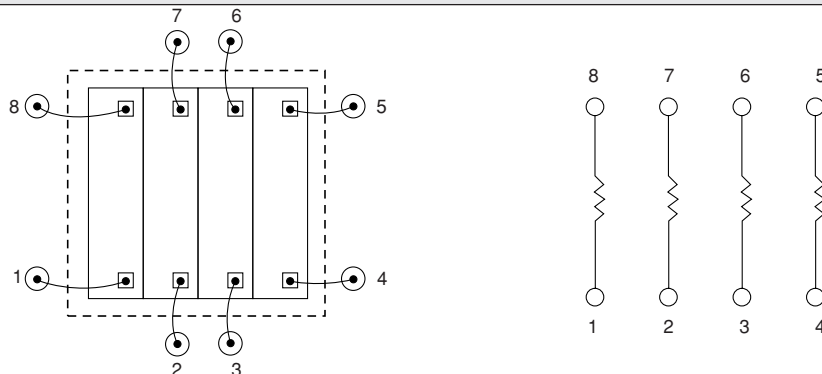


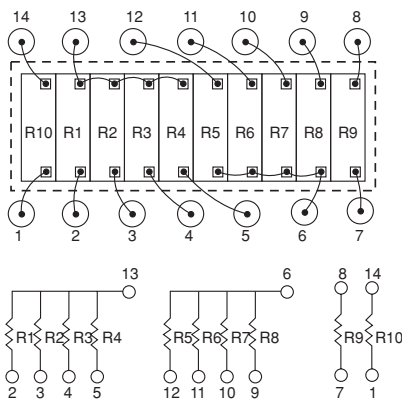


FIGURE 3 - SAMPLE CIRCUIT DESIGNS AND CHIP LAYOUTS

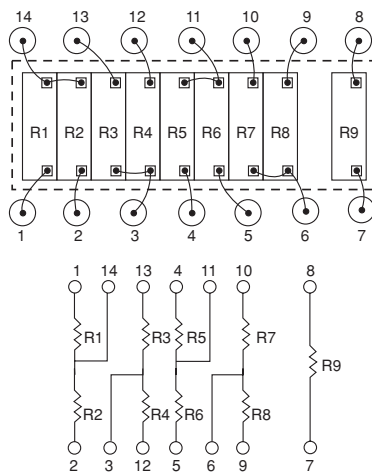
NOTE:

Usable area is represented by the dotted lines— a rectangle 0.150 Inches x 0.500 Inches. Illustrations not to scale. Chips shown undersize for clarity. Drawing view is from the top looking down into the package.

TWO DECADES OF BCD LADDER PLUS TWO SCALING RESISTORS



FOUR DIVIDERS PLUS APPLICATION RESISTOR



TEN RESISTOR DIVIDER

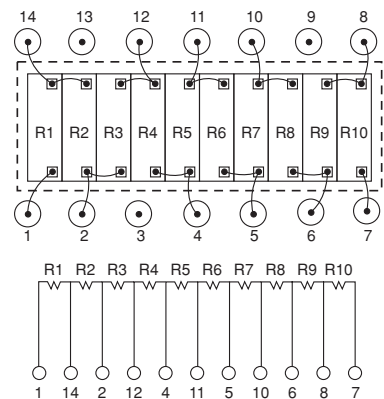
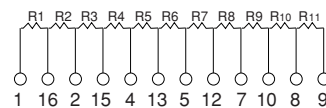
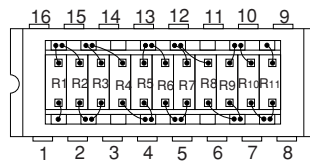


FIGURE 4 - SAMPLE CIRCUIT DESIGNS AND CHIP LAYOUTS

NOTE: Usable area is represented by the dotted lines— a rectangle 0.150 Inches x 0.600 Inches. Illustrations not to scale. Chips shown undersize for clarity. Drawing view is from the top looking down into the package.

ELEVEN RESISTOR DIVIDER



EIGHT RESISTOR PACKAGE

